

LINEAR TECHNOLOGY MATERIALS DECLARATION

lt1460hcs3-10#trpbf

(Engineering Calculation)

SOT-23

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TOTAL MASS (g) : 0.013164

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.000481 | 1000000 | 36538.46875 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu [HD] | Copper (Cu) | 7440-50-8 | 0.003510 | 975000 | 266632.0625 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000083 | 23000 | 6304.97460938 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000001 | 400 | 75.9635543823 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000006 | 1600 | 455.781311035 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.003600 | 1000000 | 273468.75 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000227 | 1000000 | 17259.5253906 | | |
| | | External Plating Total: | | | | 0.000227 | 1000000 | 17259.5253906 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000036 | 1000000 | 2734.68798828 | | |
| Internal Plating Total: | | | | 0.000036 | 1000000 | 2734.68798828 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000281 | 750000 | 21345.7578125 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000094 | 250000 | 7140.57421875 | | |
| Die Attach Total: | | | | 0.000375 | 1000000 | 28486.3320312 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.000488 | 58000 | 37070.2109375 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.007485 | 890000 | 568587.1875 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000421 | 50000 | 31980.65625 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000017 | 2000 | 1291.38037109 | | |
| | | Encapsulation Total: | | | | 0.008411 | 1000000 | 638929.375 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000034 | 1000000 | 2582.76074219 | | |
| | | | | | TOTAL MASS (g) : | 0.013164 | | |